

# SPLC 2016

The 20th International Systems and Software Product Line Conference:  
September 19th to 23rd, 2016 Beijing, China



## IMPORTANT DATES

Abstract Submission:	<b>March 7, 2016</b>
Paper Submission:	<b>March 18, 2016</b>
Notification of Acceptance:	April 25, 2016
Camera-ready Paper Due:	May 23, 2016
Conference:	Sept. 19-23, 2016

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## Software Industry Track – Call For Papers

The Systems and Software Product Line Conference (SPLC) is a premier forum where researchers, practitioners, and educators can present and discuss the most recent ideas, trends, experiences, and challenges in the area of software and system product lines engineering.

The 20th SPLC will take place in Beijing, China, September 19-23, 2016.

For more than a decade, organizations have been taking advantage of software product line practices to achieve business advantages in time to market, cost, quality, and agility. They have encountered a wide range of challenges, successes, and adaptations in their software product line experience. In addition, more and more organizations are opening up products and platforms to external contributions, to leverage the innovation power and network effects of software ecosystems.

We are seeking contributions from industry that share their challenges, successes, and adaptations of existing practices in all stages of maturity.

### Topics (include but are not limited to)

- Introducing PLE to an organization
- Software ecosystems and supply chains in industry context
- Business ecosystems around product line engineering
- Process issues, e.g. combining PLE with agile processes
- Scoping of product/solution portfolios and assets
- Product line architectures, design, validation and assessment
- Variability management in and between all stages of the life-cycle
- Guidance and governance PLE tools and methods
- Product line testing, version and configuration management
- Disruptive innovations and its effects on software product line
- Non-traditional applications of product line concepts

### Submissions/Publishing:

- *Full papers* reporting experience from industrial applications and projects. The papers in this category must provide sufficient context of the problems identified or addressed, describe clear requirements and/or experience in solving them, provide an assessment of benefits and drawbacks or other lessons learned, and explain why the contribution is innovative or valuable for others.
- *Short papers* describing, from an industrial perspective, early returns on new product line and software ecosystem applications and projects, or other shorter industry topics of interest.

The page limit is 10 pages for full papers and 5 pages for short papers. Submissions should follow the ACM SIG proceedings format (<http://www.acm.org/publications/article-templates/proceedings-template.html/>) and will be reviewed by at least three members of the SPLC 2016 Software Industry Track program committee.

The SPLC proceedings will be published by ACM in the ACM Digital Library within its International Conference Proceedings Series.

### Submission System:

- *EasyChair*: <https://easychair.org/conferences/?conf=splc2016>

### Further Information:

- For all further information please refer to [www.splc2016.net](http://www.splc2016.net)